

SEAM-20-02.0-S-10-2-A-K-TR SEAM-30-02.0-S-08-2-A-K-TR SEAM-30-03.5-S-04-2-A-K-TR

(1.27 mm) .050"

SEAM SERIES

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIEL

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material: Contact Material: Copper Alloy Operating Temp Range: -55 °C to +125 °C Current Rating (7 mm stack height): 2.7 A per pin (10 adjacent pins powered) Plating: Au or Šn over 50 μ" (1.27 μm) Ni

Working Voltage: 240 VA RoHS Compliant:

Lead-Free Solderable:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

Visit www.samtec.com/standards for more information.

MATED HEIGHTS SEAF LEAD STYLE SEAM LEAD -05.0 -06.0 -06.5 -07.5 STYLE 7 mm 8.5 mm 9.5 mm -02.08 mm -03.0 8 mm 9 mm 9.5 mm 10.5 mn -03.5 8.5 mm 9.5 mm 10 mm 11 mm -06.5 13 mm 11.5 mm 12.5 mm 14 mm -07.0 12 mm 13 mm 13.5 mm 14.5 mm -09.0 15.5 mn 16.5 mr -11.0 16 mm 17 mm 17.5 mm 18.5 mm

Notes: Patented

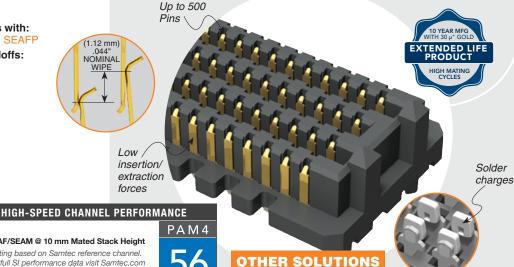
IPC-A-610F and IPC J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.



SEAM

B



SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

NO. PINS

PER ROW

Up to 560 pins

PLATING NO. OF **OPTION ROWS**

SOLDER **TYPE**







·10. -15, -20,30. –40. -

(-10 only available in 04 row) (-15 is only available in 4 Row with -02.0 lead style and 10 row with any lead style)

NO. OF

LEAD STYLE from chart

LEAD

STYLE

Matte Tin on solder tail -S = 30 µ" (0.76 µm) Gold on contact area

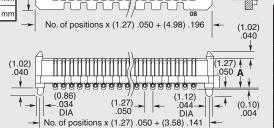
= 10 µ"

(0.25 µm)

Gold on

contact area

В ROWS -04 (7.06) .278 (9.60) .378 -05. -06 Matte Tin on -08 (12.14) .478 solder tail -10(14.68) .578 (1.27) .050



-04=Four Rows (-06.5 not available)

-05 =Five Rows (-06.5 not available)

-06=Six Rows (-06.5 not available)

-08=Eight Rows -10=Ten Rows

.050

DV

LEAD STYLE	Α
-02.0	(4.60) .181
-03.0	(5.59) .220
-03.5	(6.10) .240
-06.5	(9.14) .360
-07.0	(9.60) .378
-09.0	(11.60) .457
-11.0	(13.60) .535

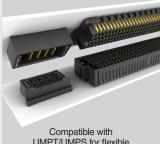
-1 Tin/Lead Alloy Solder Charge

-2 = Lead-Free Solder Charge = Alignment Pins (Required. Arrays will not self-center on solder pads)

> = Polyimide film Pick & Place Pad

-TR =Tape & Reel

POWER/SIGNAL APPLICATION



UMPT/UMPS for flexible two-piece power/signal solutions